

Features

- Free from secondary breakdown
- Low power drive requirement
- Ease of paralleling
- Low C_{ISS} and fast switching speeds
- High input impedance and high gain

Applications

- Motor controls
- Converters
- **Amplifiers**
- Switches
- Power supply circuits
- Drivers (relays, hammers, solenoids, lamps, memories, displays, bipolar transistors, etc.)

General Description

The Supertex VN2106 is an enhancement-mode (normallyoff) transistor that utilizes a vertical DMOS structure and Supertex's well-proven silicon-gate manufacturing process. This combination produces a device with the power handling capabilities of bipolar transistors, and the high input impedance and positive temperature coefficient inherent in MOS devices. Characteristic of all MOS structures, this device is free from thermal runaway and thermally-induced secondary breakdown.

Supertex's vertical DMOS FETs are ideally suited to a wide range of switching and amplifying applications where very low threshold voltage, high breakdown voltage, high input impedance, low input capacitance, and fast switching speeds are desired.

Ordering Information

Device	Package Option TO-92	BV _{DSS} /BV _{DGS} (V)	$R_{DS(ON)} \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ $		
VN2106	VN2106N3-G	60	4.0		





-G indicates package is RoHS compliant ('Green')

Absolute Maximum Ratings

Parameter	Value			
Drain-to-Source voltage	BV _{DSS}			
Drain-to-Gate voltage	BV _{DGS}			
Gate-to-Source voltage	±20V			
Operating and storage temperature	-55°C to +150°C			
Soldering temperature*	+300°C			

Absolute Maximum Ratings are those values beyond which damage to the device may occur. Functional operation under these conditions is not implied. Continuous operation of the device at the absolute rating level may affect device reliability. All voltages are referenced to device ground.

Distance of 1.6mm from case for 10 seconds.

Pin Configuration



Product Marking



YY = Year Sealed WW = Week Sealed _ = "Green" Packaging

Package may or may not include the following marks: Si or



Thermal Characteristics

Package	l _D (continuous) [†] (mA)	I _D (pulsed) (A)	Power Dissipation @T _c = 25°C (W)	θ _{jc} (°C/W)	θ _{ja} (°C/W)	Ι _{DR} [†] (mA)	I _{DRM} (A)
TO-92	300	1.0	1.0	125	170	300	1.0

Notes:

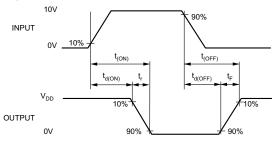
Electrical Characteristics (T_A = 25°C unless otherwise specified)

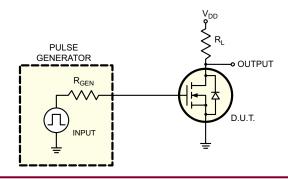
Sym	Parameter		Min Typ Max		Units	Conditions	
BV _{DSS}	Drain-to-source breakdown voltage	60	-	-	V	$V_{GS} = 0V, I_D = 1.0 \text{mA}$	
$V_{GS(th)}$	Gate threshold voltage	0.8	-	2.4	V	$V_{GS} = V_{DS}$, $I_{D} = 1.0$ mA	
$\Delta V_{GS(th)}$	Change in V _{GS(th)} with temperature	-	-3.8	-5.5	mV/°C	$V_{GS} = V_{DS}$, $I_{D} = 1.0$ mA	
l _{GSS}	Gate body leakage current	_	0.1	100	nA	$V_{GS} = \pm 20V$, $V_{DS} = 0V$	
	Zero gate voltage drain current		-	1.0		$V_{GS} = 0V, V_{DS} = Max Rating$	
l _{DSS}			-	100	μA	$V_{DS} = 0.8$ Max Rating, $V_{GS} = 0V$, $T_{A} = 125^{\circ}C$	
I _{D(ON)}	On-state drain current	0.6	-	-	Α	$V_{GS} = 10V, V_{DS} = 25V$	
Б		-	4.5	6.0		V _{GS} = 5.0V, I _D = 75mA	
R _{DS(ON)}	Static drain-to-source on-state resistance	-	3.0	4.0	Ω	V _{GS} = 10V, I _D = 500mA	
$\Delta R_{DS(ON)}$	Change in R _{DS(ON)} with temperature	-	0.7	1.0	%/°C	$V_{GS} = 10V, I_{D} = 500mA$	
G _{FS}	Forward transconductance	150	400	-	mmho	$V_{DS} = 25V, I_{D} = 500mA$	
C _{ISS}	Input capacitance	-	35	50		V _{GS} = 0V,	
C _{oss}	Common source output capacitance	1	13	25	pF	$V_{DS} = 25V,$	
C _{RSS}	Reverse transfer capacitance	-	4.0	5.0		f = 1.0MHz	
t _{d(ON)}	Turn-on delay time	-	3.0	5.0		$V_{DD} = 25V,$ $I_{D} = 600 \text{mA},$ $R_{GEN} = 25\Omega$	
t _r	Rise time	-	5.0	8.0	ns		
t _{d(OFF)}	Turn-off delay time	-	6.0	9.0			
t _f	Fall time	-	5.0	8.0		GEN	
V_{SD}	Diode forward voltage drop	-	1.2	1.8	V	$V_{GS} = 0V, I_{SD} = 600 \text{mA}$	
t _{rr}	Reverse recovery time	-	400	-	ns	$V_{GS} = 0V$, $I_{SD} = 600$ mA	

Notes:

- 1. All D.C. parameters 100% tested at 25°C unless otherwise stated. (Pulse test: 300µs pulse, 2% duty cycle.)
- 2. All A.C. parameters sample tested.

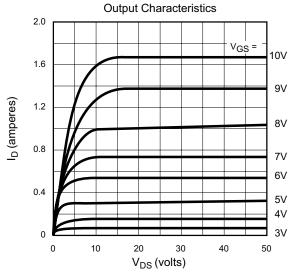
Switching Waveforms and Test Circuit

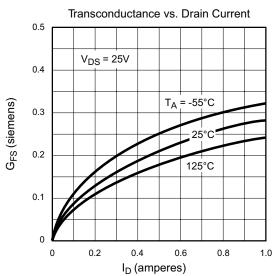


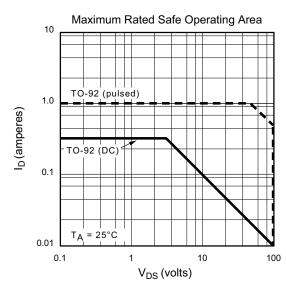


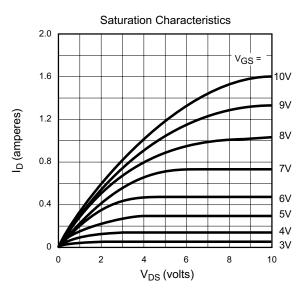
[†] I_D (continuous) is limited by max rated T_i .

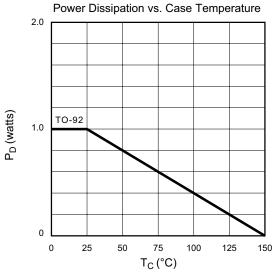
Typical Performance Curves

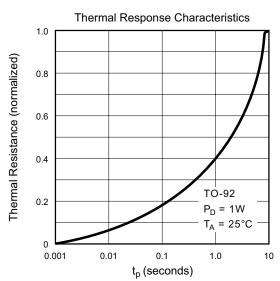




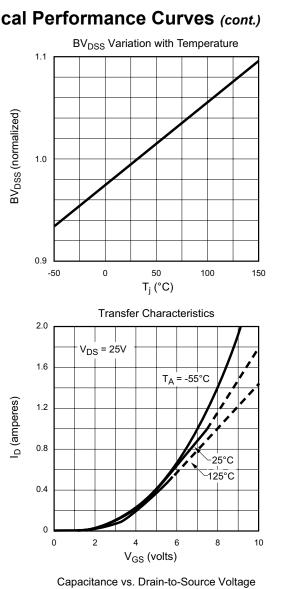


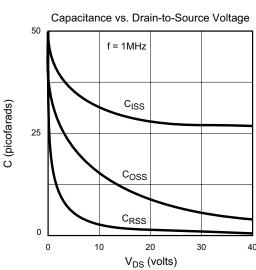


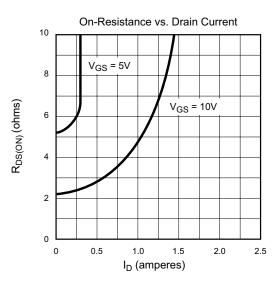


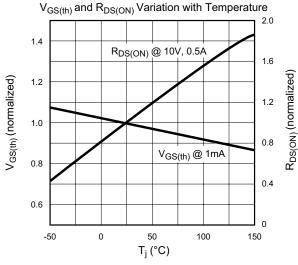


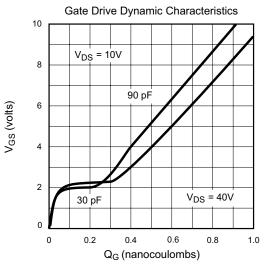
Typical Performance Curves (cont.)



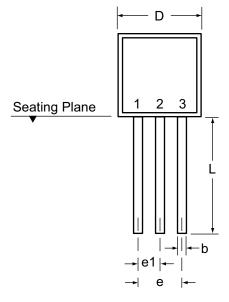


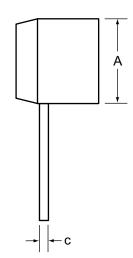






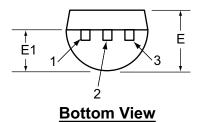
3-Lead TO-92 Package Outline (N3)





Front View

Side View



Symb	ool	Α	b	С	D	E	E1	е	e1	L
	MIN	.170	.014 [†]	.014 [†]	.175	.125	.080	.095	.045	.500
Dimensions (inches)	NOM	-	-	-	-	-	-	-	-	-
	MAX	.210	.022 [†]	.022 [†]	.205	.165	.105	.105	.055	.610*

JEDEC Registration TO-92.

Drawings not to scale.

Supertex Doc.#: DSPD-3TO92N3, Version D080408.

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information go to http://www.supertex.com/packaging.html.)

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^{*} This dimension is not specified in the original JEDEC drawing. The value listed is for reference only.

[†] This dimension is a non-JEDEC dimension.